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FDZ209N

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FAIRCHILD SEMICONDUCTOR®

May 2004

FDZ209N

60V N-Channel PowerTrench® BGA MOSFET

General Description

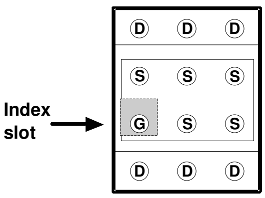
Combining Fairchild's advanced PowerTrench process with state-of-the-art BGA packaging, the FDZ209N minimizes both PCB space and $R_{DS(ON)}$. This BGA MOSFET embodies a breakthrough in packaging technology which enables the device to combine excellent thermal transfer characteristics, high current handling capability, ultra-low profile packaging, low gate charge, and low $R_{DS(ON)}$.

Applications

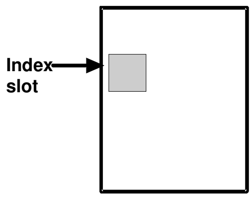
- Solenoid Drivers

Features

- 4 A, 60 V. $R_{DS(ON)}$ = 80 mΩ @ V_{GS} = 5 V
- Occupies only 5 mm^2 of PCB area: only 55% of the area of SSOT-6
- Ultra-thin package: less than 0.80 mm height when mounted to PCB
- Outstanding thermal transfer characteristics: 4 times better than SSOT-6
- Ultra-low Q_g x $R_{DS(ON)}$ figure-of-merit
- High power and current handling capability



Bottom



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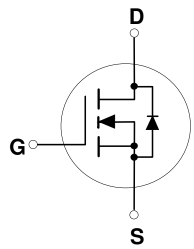


Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-Source Voltage		60	V
V_{GSS}	Gate-Source Voltage		±20	V
I_D	Drain Current – Continuous	(Note 1a)	4	A
	– Pulsed		20	
P_D	Power Dissipation (Steady State)	(Note 1a)	2	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range		–55 to +150	°C

Thermal Characteristics

Symbol	Parameter		Ratings	Units
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	64	°C/W
$R_{\theta JB}$	Thermal Resistance, Junction-to-Ball	(Note 1)	8	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	(Note 1)	0.7	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
209N	FDZ209N	7''	8mm	3000 units

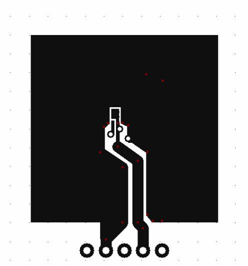
Electrical Characteristics

T_A = 25°C unless otherwise noted

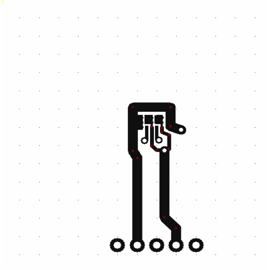
Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Drain-Source Avalanche Ratings (Note 2)						
W_{DSS}	Drain-Source Avalanche Energy	Single Pulse, V_{DD} = 30 V, I_D= 4 A			90	mJ
I_{AR}	Drain-Source Avalanche Current				4	A
Off Characteristics						
BV_{DSS}	Drain–Source Breakdown Voltage	V_{GS} = 0 V, I_D = 250 µA	60			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		59		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 48 V, V_{GS} = 0 V			1	µA
I_{GSS}	Gate–Body Leakage.	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics (Note 2)						
$V_{GS(th)}$	Gate Threshold Voltage	V_{DS} = V_{GS}, I_D = 250 µA	1	2.5	3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 µA, Referenced to 25°C		–6		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	V_{GS} = 5 V, I_D = 4 A V_{GS} = 5 V, I_D = 4 A, T_J=125°C		60 91	80 130	mΩ
g_{FS}	Forward Transconductance	V_{DS} = 5 V, I_D = 4 A		12		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 30 V, V_{GS} = 0 V, f = 1.0 MHz		657		pF
C_{oss}	Output Capacitance			76		pF
C_{rss}	Reverse Transfer Capacitance			32		pF
R_G	Gate Resistance	V_{GS} = 15 mV, f = 1.0 MHz		1.5		Ω
Switching Characteristics (Note 2)						
$t_{d(on)}$	Turn–On Delay Time	V_{DD} = 30 V, I_D = 1 A, V_{GS} = 5 V, R_{GEN} = 6 Ω		18	32	ns
t_r	Turn–On Rise Time			4	8	ns
$t_{d(off)}$	Turn–Off Delay Time			15	27	ns
t_f	Turn–Off Fall Time			8	16	ns
Q_g	Total Gate Charge	V_{DS} = 30 V, I_D = 4 A, V_{GS} = 5 V		6.3	9	nC
Q_{gs}	Gate–Source Charge			2.5		nC
Q_{gd}	Gate–Drain Charge			2.5		nC
Drain–Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain–Source Diode Forward Current				1.7	A
V_{SD}	Drain–Source Diode Forward Voltage	V_{GS} = 0 V, I_S = 1.7 A (Note 2)		0.77	1.2	V
t_{rr}	Diode Reverse Recovery Time	I_F = 4A, d_{iF}/d_t = 100 A/µs (Note 2)		27		nS
Q_{rr}	Diode Reverse Recovery Charge			45		nC

Notes:

1. $R_{\theta JA}$ is determined with the device mounted on a 1 in² 2 oz. copper pad on a 1.5 x 1.5 in. board of FR-4 material. The thermal resistance from the junction to the circuit board side of the solder ball, $R_{\theta JB}$, is defined for reference. For $R_{\theta JC}$, the thermal reference point for the case is defined as the top surface of the copper chip carrier. $R_{\theta JC}$ and $R_{\theta JB}$ are guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) 64°C/W when mounted on a 1in² pad of 2 oz copper, 1.5" x 1.5" x 0.062" thick PCB

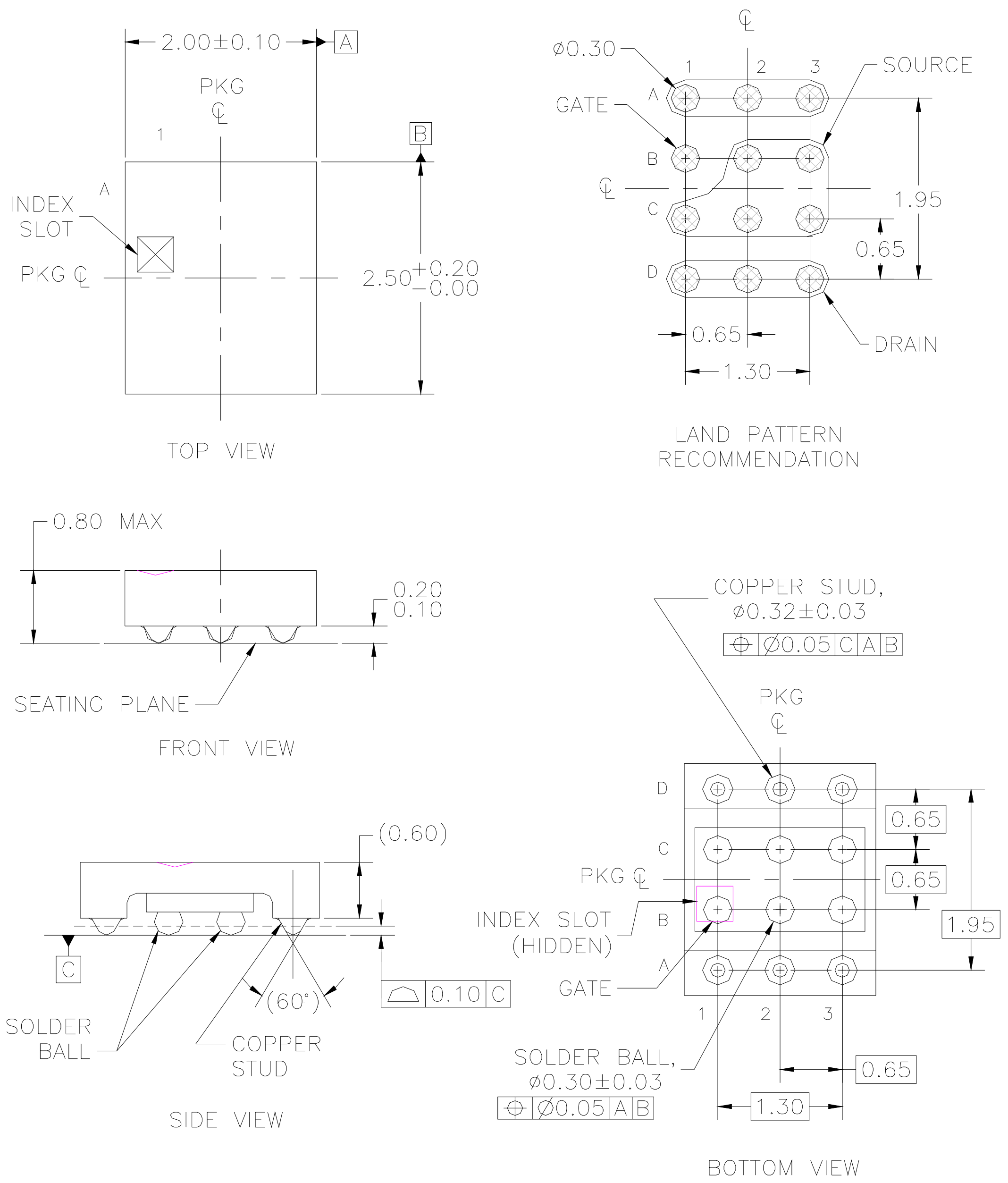


b) 128°C/W when mounted on a minimum pad of 2 oz copper

Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Dimensional Outline and Pad Layout



NOTES: UNLESS OTHERWISE SPECIFIED

A) ALL DIMENSIONS ARE IN MILLIMETERS.
B) NO JEDEC REGISTRATION REFERENCE AS OF JULY 1999.
C) TERMINAL CONFIGURATION TABLE.

POSITION	DESIGNATION	TYPE
A1,A2,A3, D1,D2,D3	DRAIN	COPPER STUD
B1	GATE	SOLDER BALL
B2,B3,C1,C2,C3	SOURCE	SOLDER BALL

Typical Characteristics

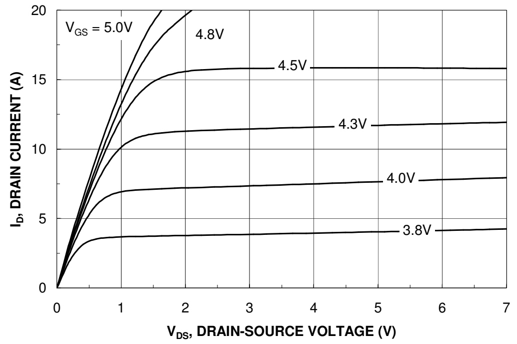


Figure 1. On-Region Characteristics.

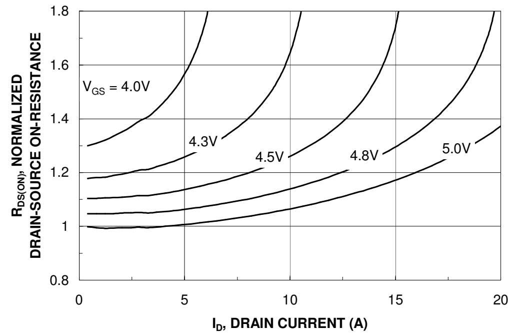


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

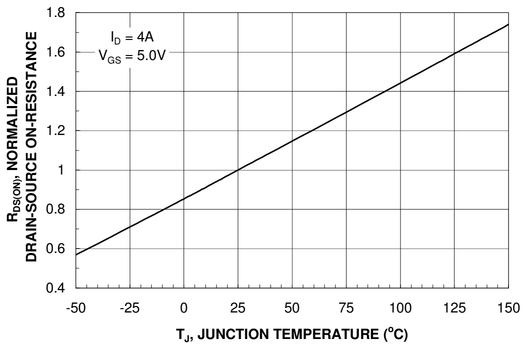


Figure 3. On-Resistance Variation with Temperature.

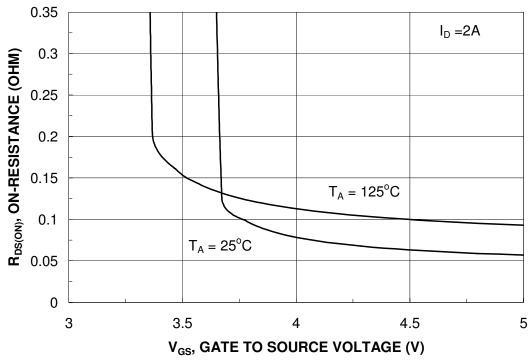


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

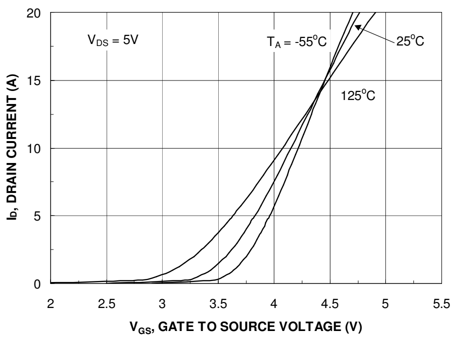


Figure 5. Transfer Characteristics.

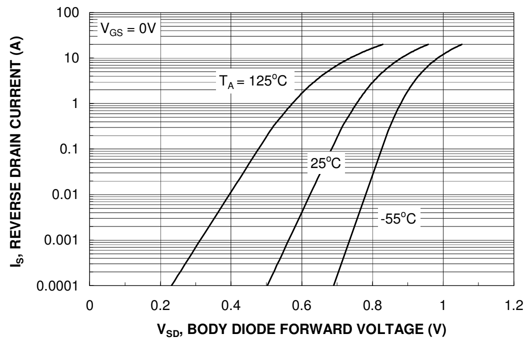


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics

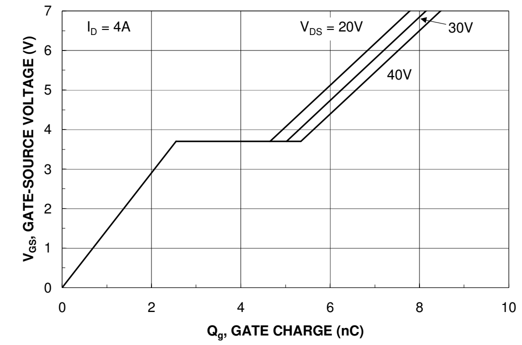


Figure 7. Gate Charge Characteristics.

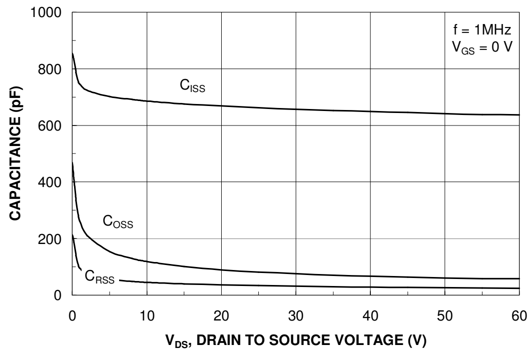


Figure 8. Capacitance Characteristics.

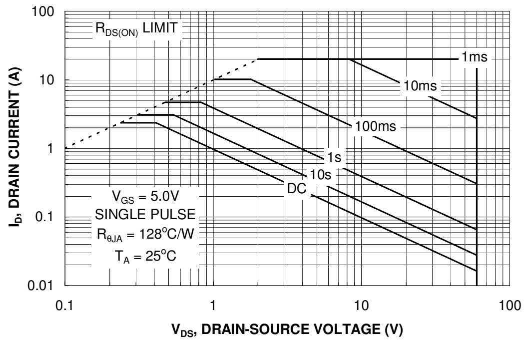


Figure 9. Maximum Safe Operating Area.

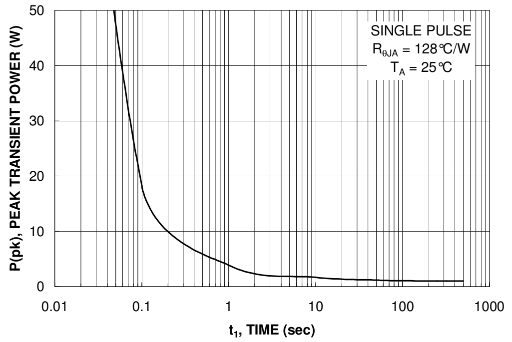


Figure 10. Single Pulse Maximum Power Dissipation.

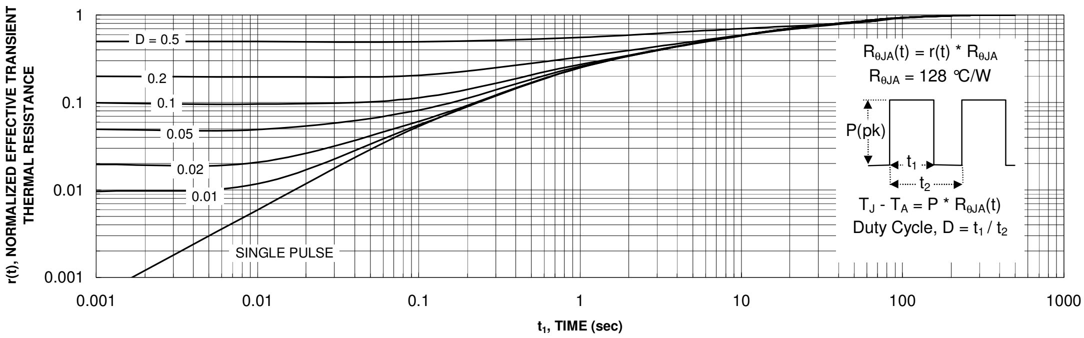


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b.
Transient thermal response will change depending on the circuit board design.

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